Quarterly Financial Result (Supplementary Materials)

Quarter 3: three months ended
September 30, 2026

November12, 2026
Code: 6871

MICRONICS JAPAN CO., LTD.

© 2026 MICRONICS JAPAN CO., LTD.

Disclaimer

The contents of this presentation were compiled based on information readily available at the time of this presentation. Outlooks and other forward-looking statements are subject to change based on many uncertain worldwide factors including but not limited to market conditions, competition as well as semiconductor / LCD industry trends. Accordingly, please take note that the actual performance of the Company may vary considerably from the information and statements made in this presentation.

This English document is translated using a machine translation. You may use this for reference purposes only, fully understanding that it may include inaccurate translations. It is your sole responsibility if you rely not on the Japanese original but on this translation.

© 2026 MICRONICS JAPAN CO., LTD.

Quarterly Financial Results (Q3)

© 2026 MICRONICS JAPAN CO., LTD.

Consolidated Result Summary

(Unit : Mils. of Yen)
*Amounts less than one million yen are rounded down

	FY12/2025	FY12/2026					
	Jul.-Sep.	Apl.-Jun.	Jul.-Sep.	QoQ		YoY	
	Q3 ⓐ	Q2 ⓑ	Q3 ⓒ	(△) ⓒ-ⓑ	(%)	(△) ⓒ-ⓐ	(%)
Net Sales	17,291	28,261	32,757	+4,496	+15.9%	+15,466	+89.4%
Probe Card	16,917	27,912	32,304	+4,391	+15.7%	+15,386	+91.0%
TE ※	374	348	453	+105	+30.2%	+79	+21.2%
Gross Profit	7,683	15,217	16,976	+1,758	+11.6%	+9,292	+120.9%
Operating profit	3,730	9,909	11,436	+1,527	+15.4%	+7,706	+206.6%
Ordinary profit	3,878	10,268	12,622	+2,354	+22.9%	+8,744	+225.5%
Net Income Attributable to Owners of Parent	2,309	7,068	8,045	+977	+13.8%	+5,735	+248.3%

※ : Test Equipment

© 2026 MICRONICS JAPAN CO., LTD.

Consolidated Result Summary

(Unit : Mils. of Yen)
*Amounts less than one million yen are rounded down

	FY12/2025	FY12/2026					
	Jan.-Sep.			As of Aug.12		YoY	
	Results ⓐ	Forecast ⓑ	Results ⓒ	(△) ⓒ-ⓑ	(%)	(△) ⓒ-ⓐ	(%)
Net Sales	50,412	74,200	81,964	+7,764	+10.5%	+31,552	+62.6%
Probe Card	49,117	73,000	80,847	+7,847	+10.7%	+31,729	+64.6%
TE ※	1,295	1,100	1,117	+17	+1.6%	(177)	(13.7%)
Gross Profit	24,085	—	42,092	—	—	+18,006	+74.8%
Operating profit	11,300	22,400	26,993	+4,593	+20.5%	+15,693	+138.9%
Ordinary profit	11,273	23,100	28,883	+5,783	+25.0%	+17,610	+156.2%
Net Income Attributable to Owners of Parent	7,084	16,300	19,506	+3,206	+19.7%	+12,421	+175.3%

※ : Test Equipment

© 2026 MICRONICS JAPAN CO., LTD.

Summary of Q3 FY2026 Results

Probe card

- Sales of memory probe cards increased significantly quarter over quarter and reached a record high, driven by the bringing forward of sales in connection with production capacity expansion.
- Sales of non-memory probe cards also increased significantly quarter over quarter.
- Segment profit increased quarter over quarter, driven by contributions from high value-added products for DRAM applications.
- Orders increased significantly quarter over quarter, while strong demand for DRAM applications, particularly HBM (High Bandwidth Memory), continued.

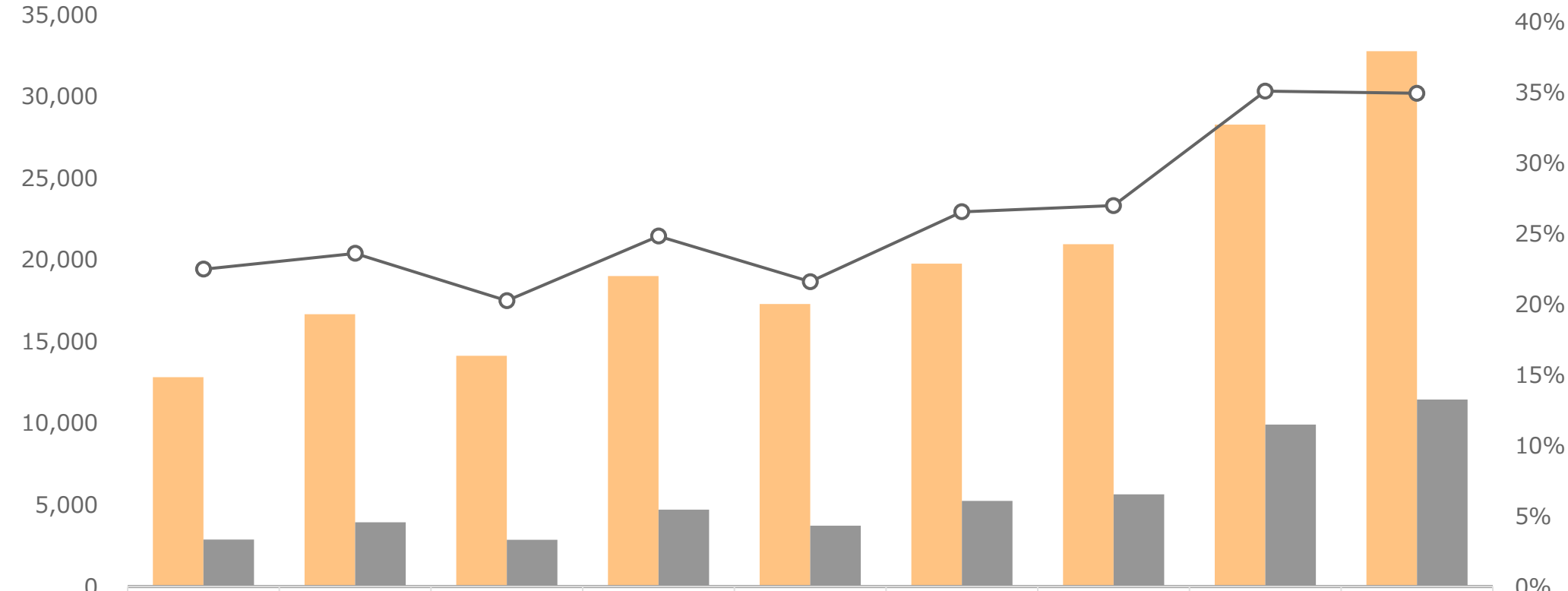
TE

- Sales slightly increased quarter over quarter, supported by solid performance in semiconductor test sockets.
- The segment loss narrowed quarter over quarter.
- Customer evaluations of Testalio semiconductor testers and Excelyze probers are ongoing with the aim of securing orders.

© 2026 MICRONICS JAPAN CO., LTD.

Quarterly Financial Result

(Mils. of Yen)

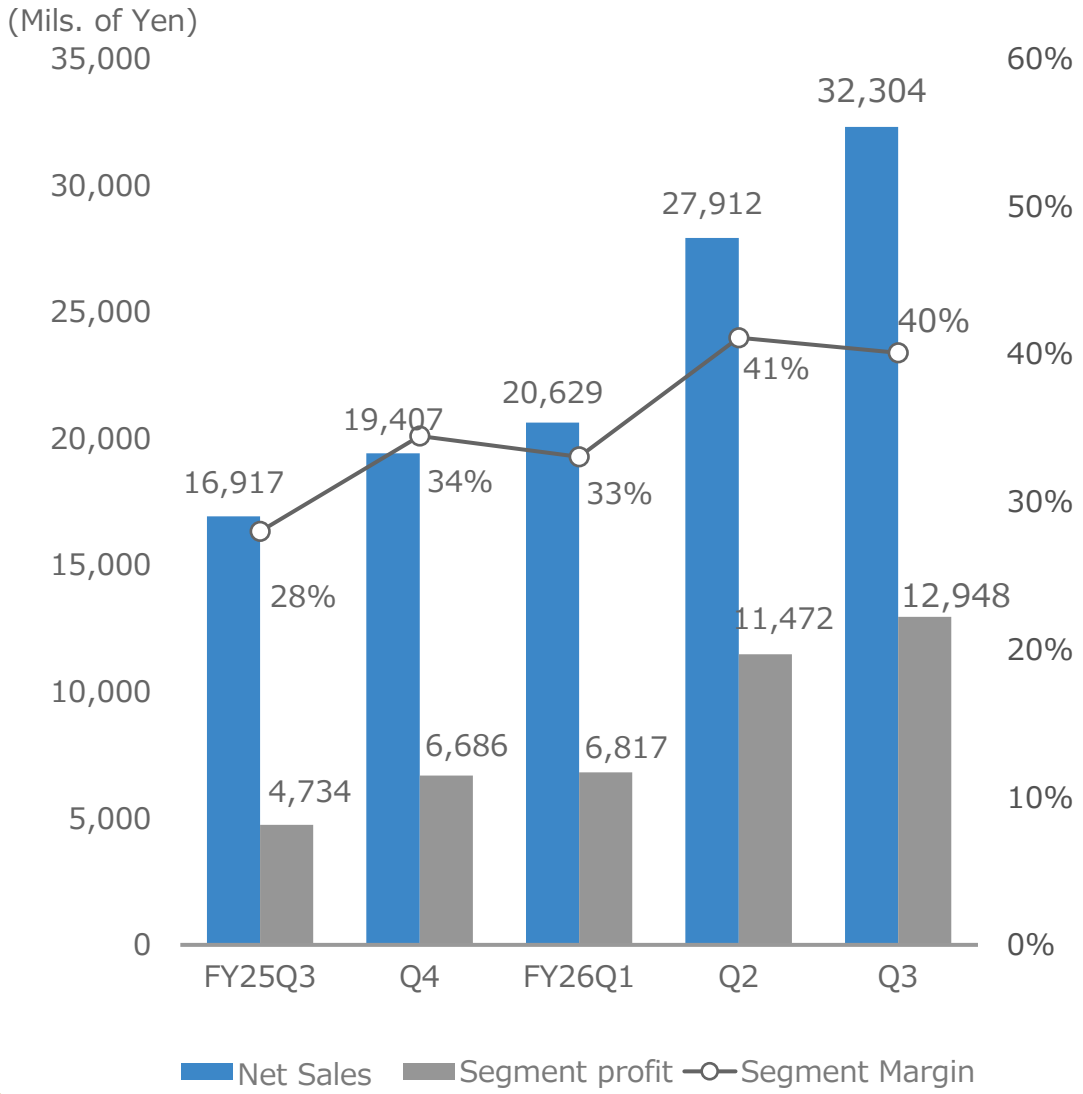


	FY24Q3	Q4	FY25Q1	Q2	Q3	Q4	FY26Q1	Q2	Q3
Net Sales	12,812	16,659	14,124	18,996	17,291	19,761	20,945	28,261	32,757
Operating profit	2,878	3,928	2,857	4,711	3,730	5,241	5,647	9,909	11,436
Operating Margin	22.5%	23.6%	20.2%	24.8%	21.6%	26.5%	27.0%	35.1%	34.9%

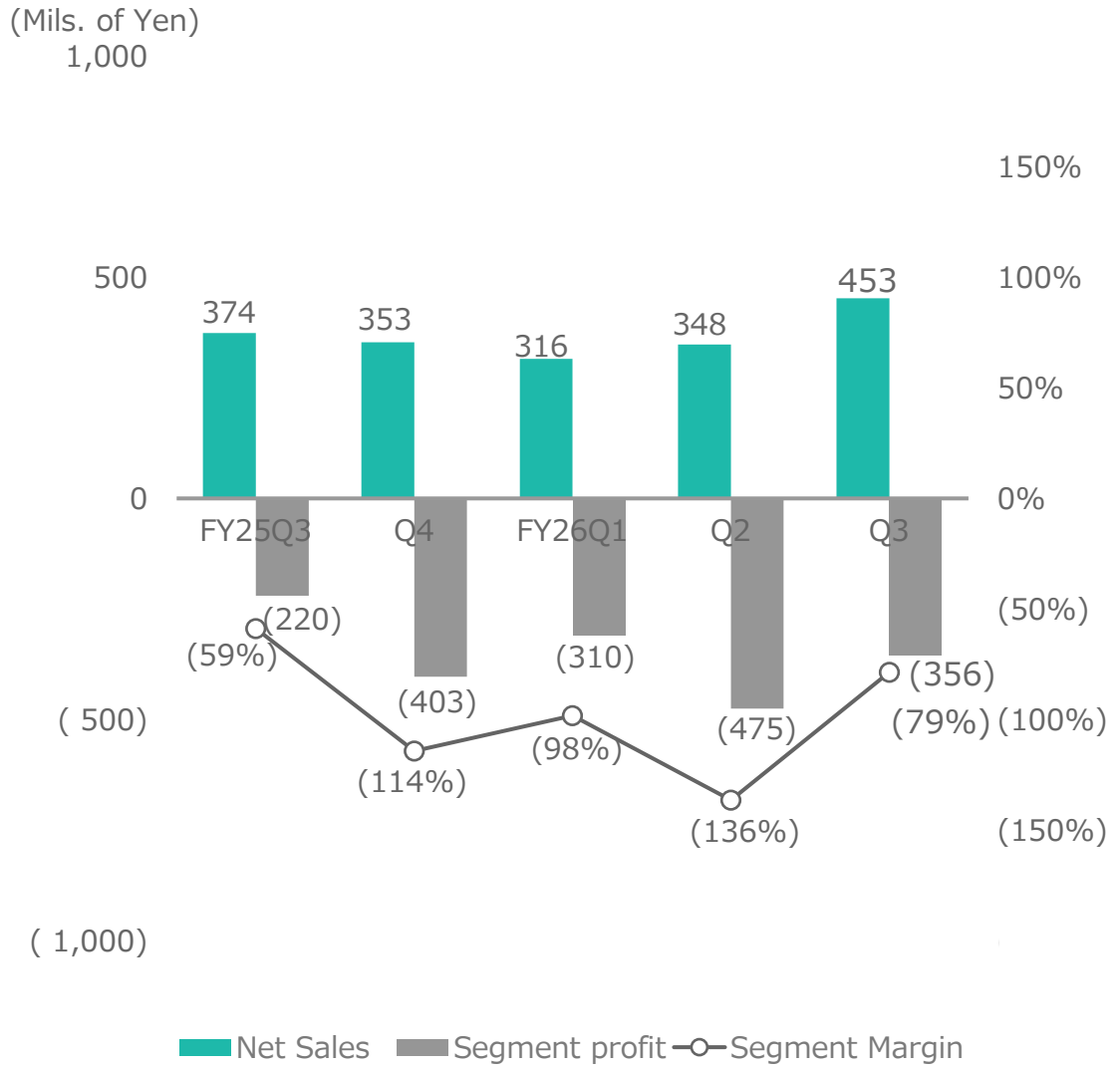
© 2026 MICRONICS JAPAN CO., LTD.

Business Condition by Segment

Probe card



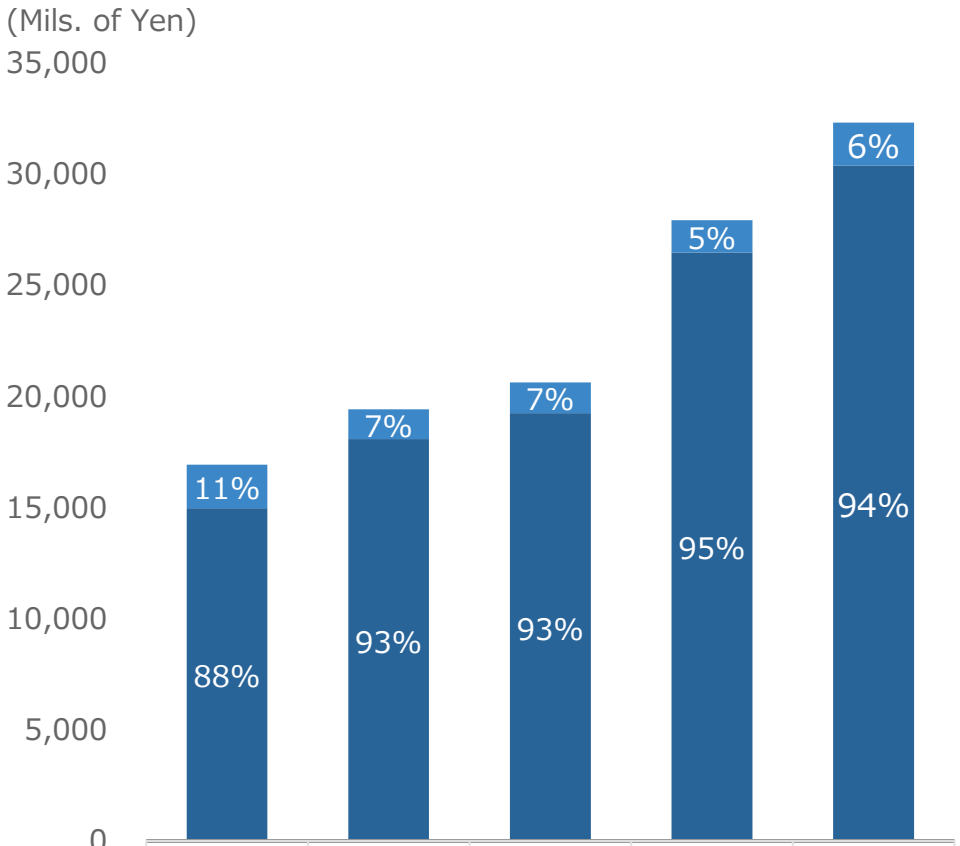
TE



© 2026 MICRONICS JAPAN CO., LTD.

Quarterly Net Sales by Product

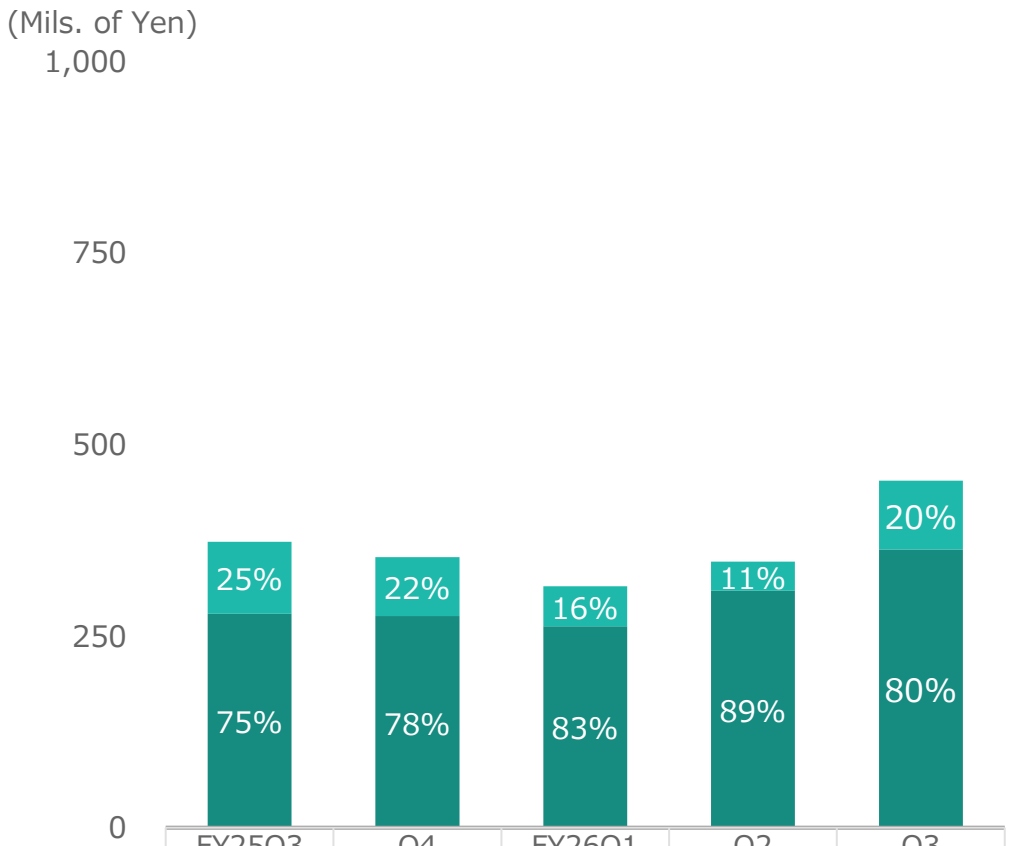
Probe card



	FY25Q3	Q4	FY26Q1	Q2	Q3
Non-Memory	1,945	1,329	1,383	1,447	1,933
Memory	14,971	18,078	19,245	26,465	30,371
total	16,917	19,407	20,629	27,912	32,304

※ Including sales of Cantilever type

TE



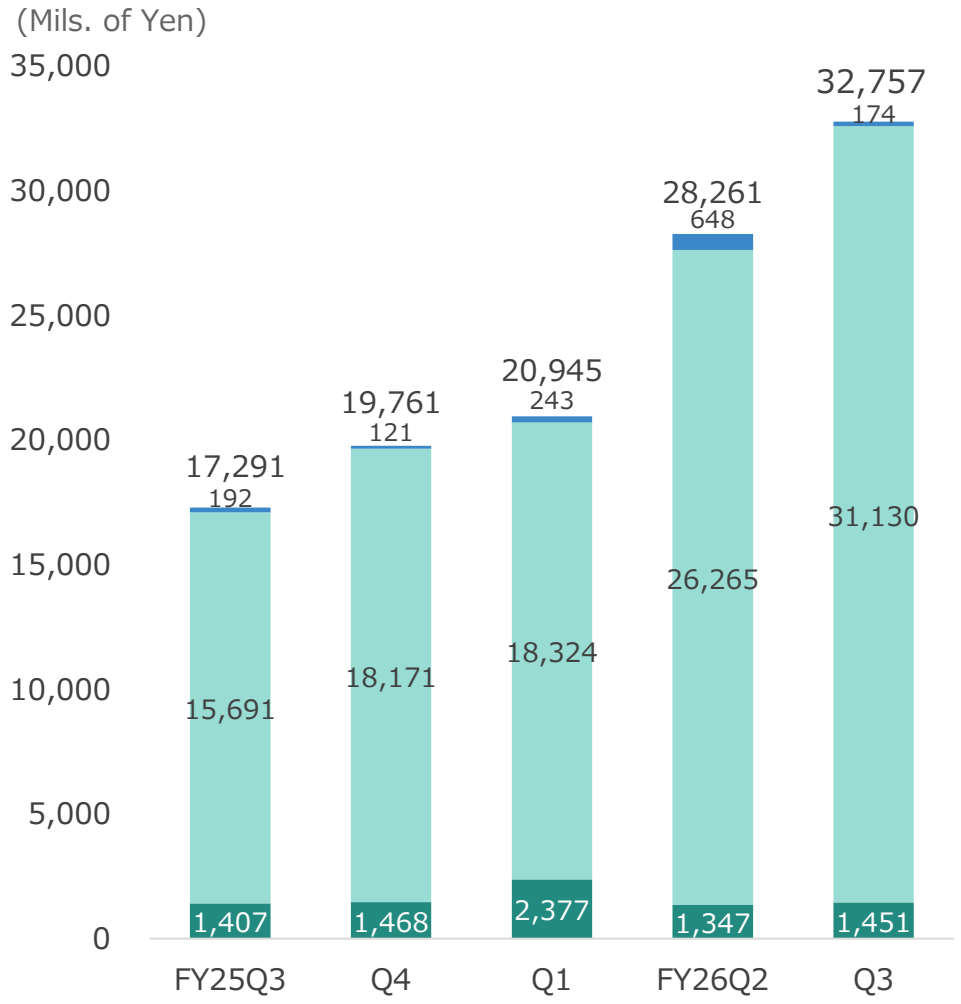
	FY25Q3	Q4	FY26Q1	Q2	Q3
Testing Equipment※1	94	77	52	38	90
Testing Device ※2	279	276	263	309	363
total	374	353	316	348	453

※1 Custom testers, Semiconductor probers, FPD test equipment, etc.
※2 Test sockets for semiconductors, Probe units for FPDs

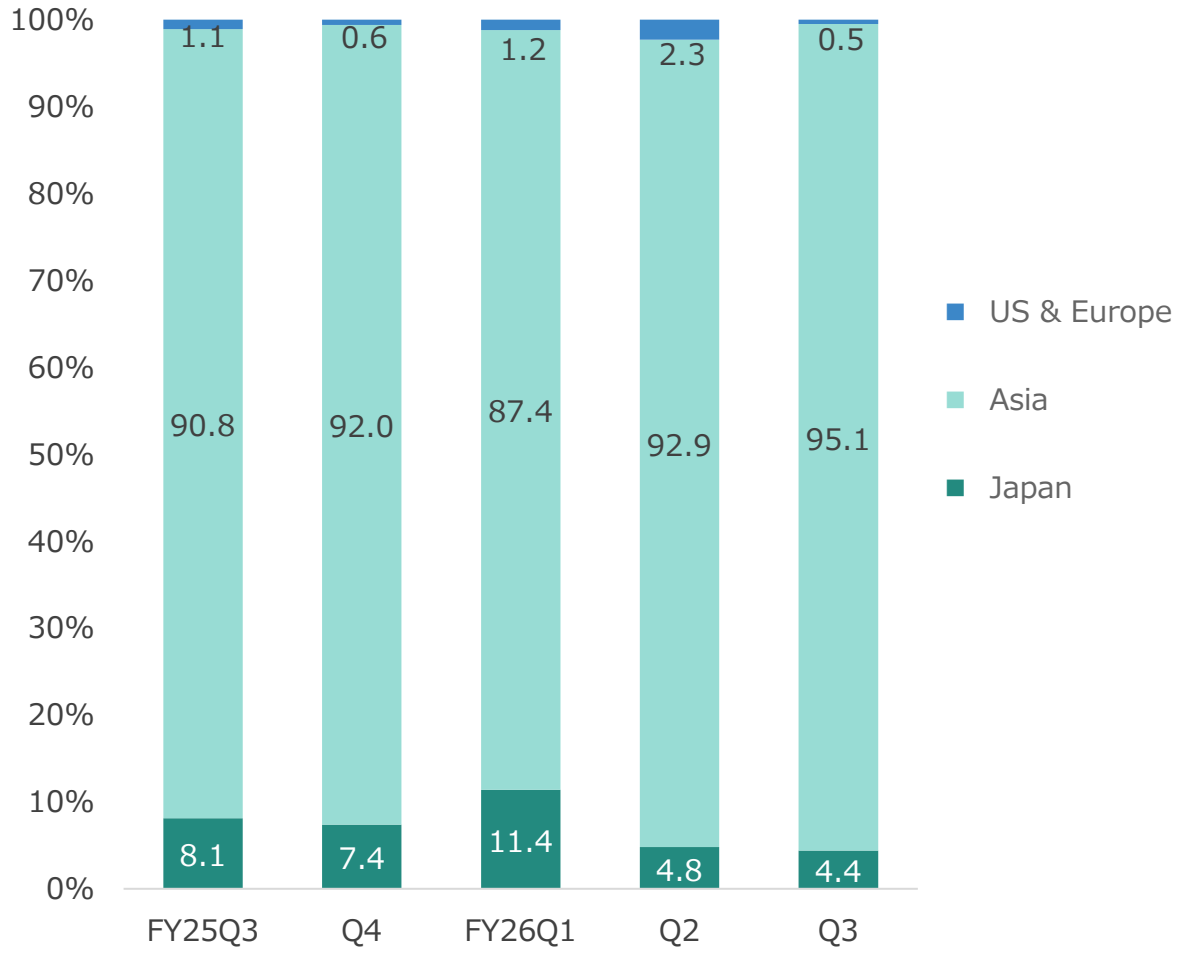
© 2026 MICRONICS JAPAN CO., LTD.

Quarterly Net Sales by Region

Net Sales



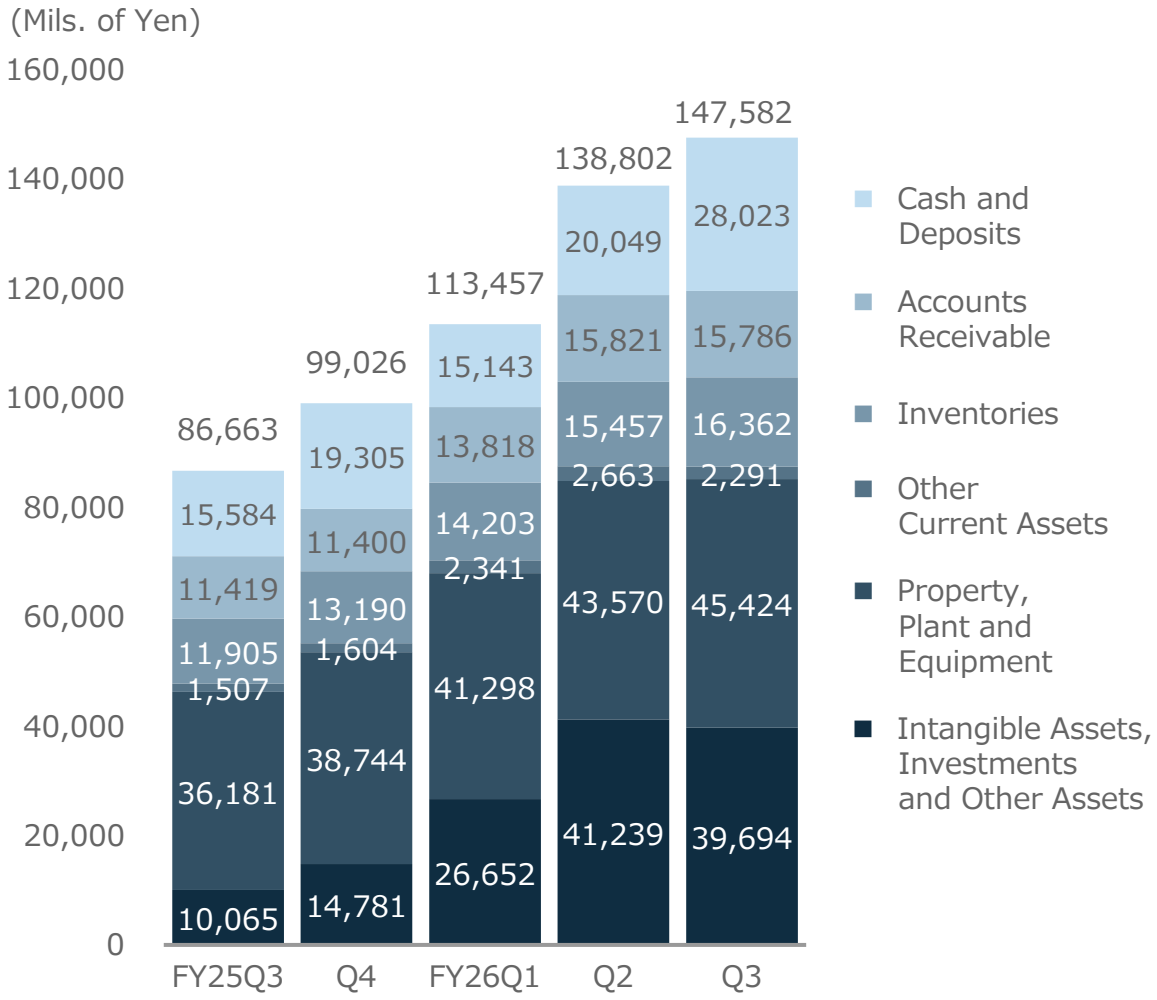
Percentage of sales



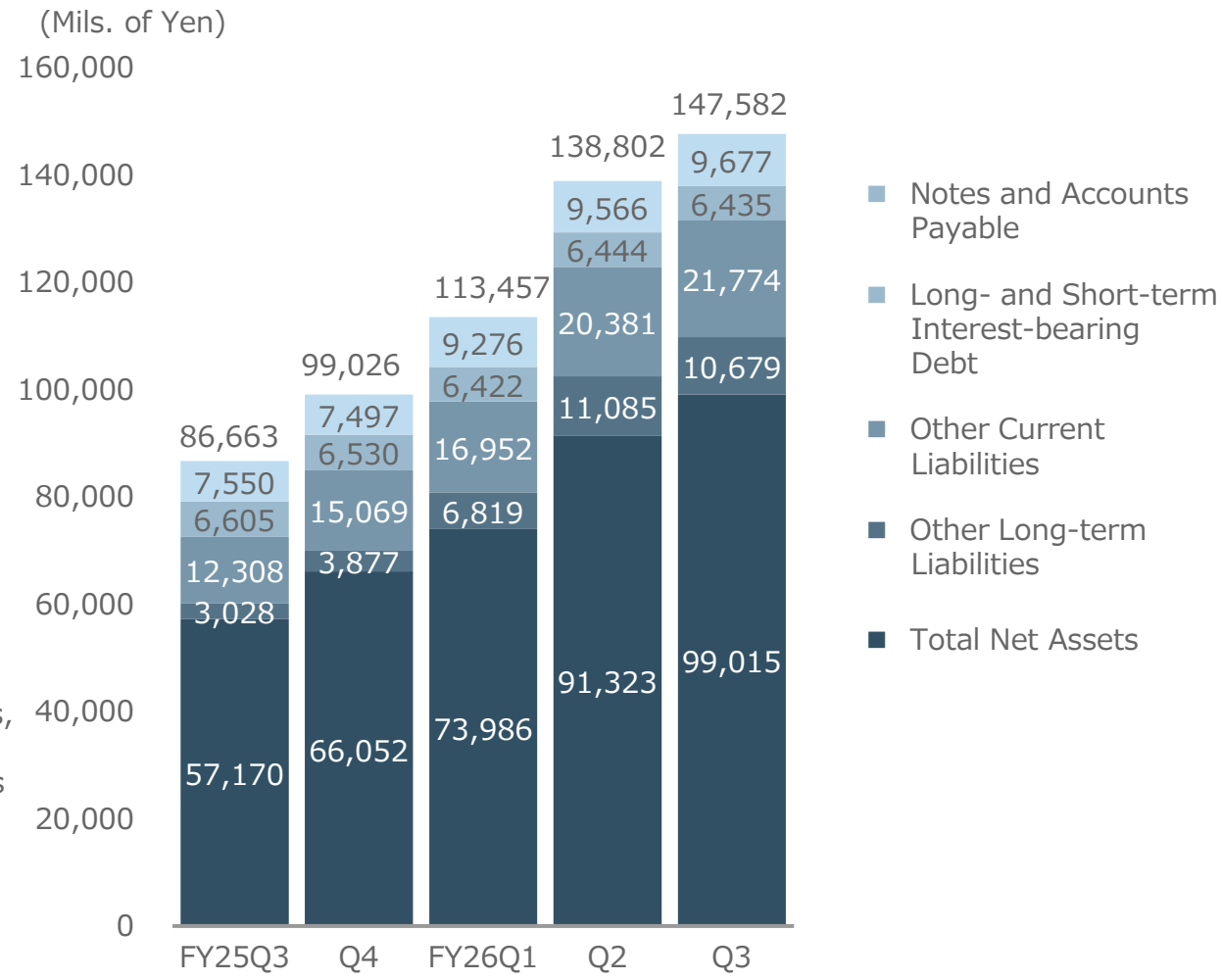
© 2026 MICRONICS JAPAN CO., LTD.

Consolidated Balance Sheet

Assets



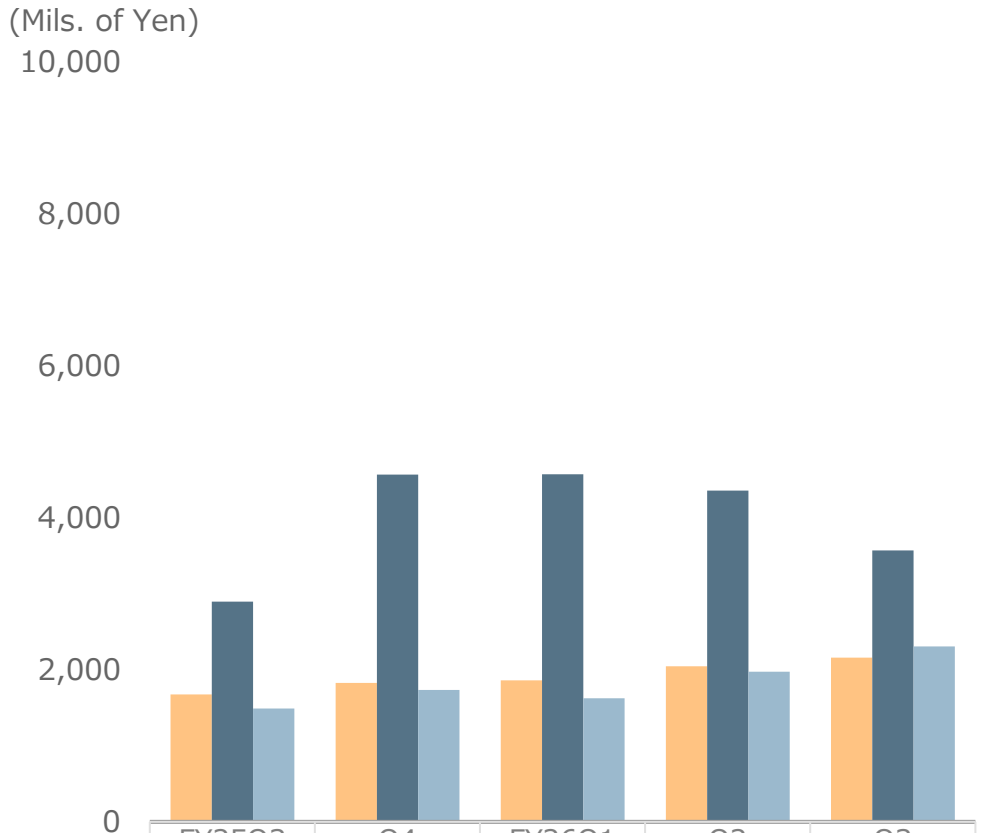
Liabilities & Net Assets



© 2026 MICRONICS JAPAN CO., LTD.

Investments/Cash Flows

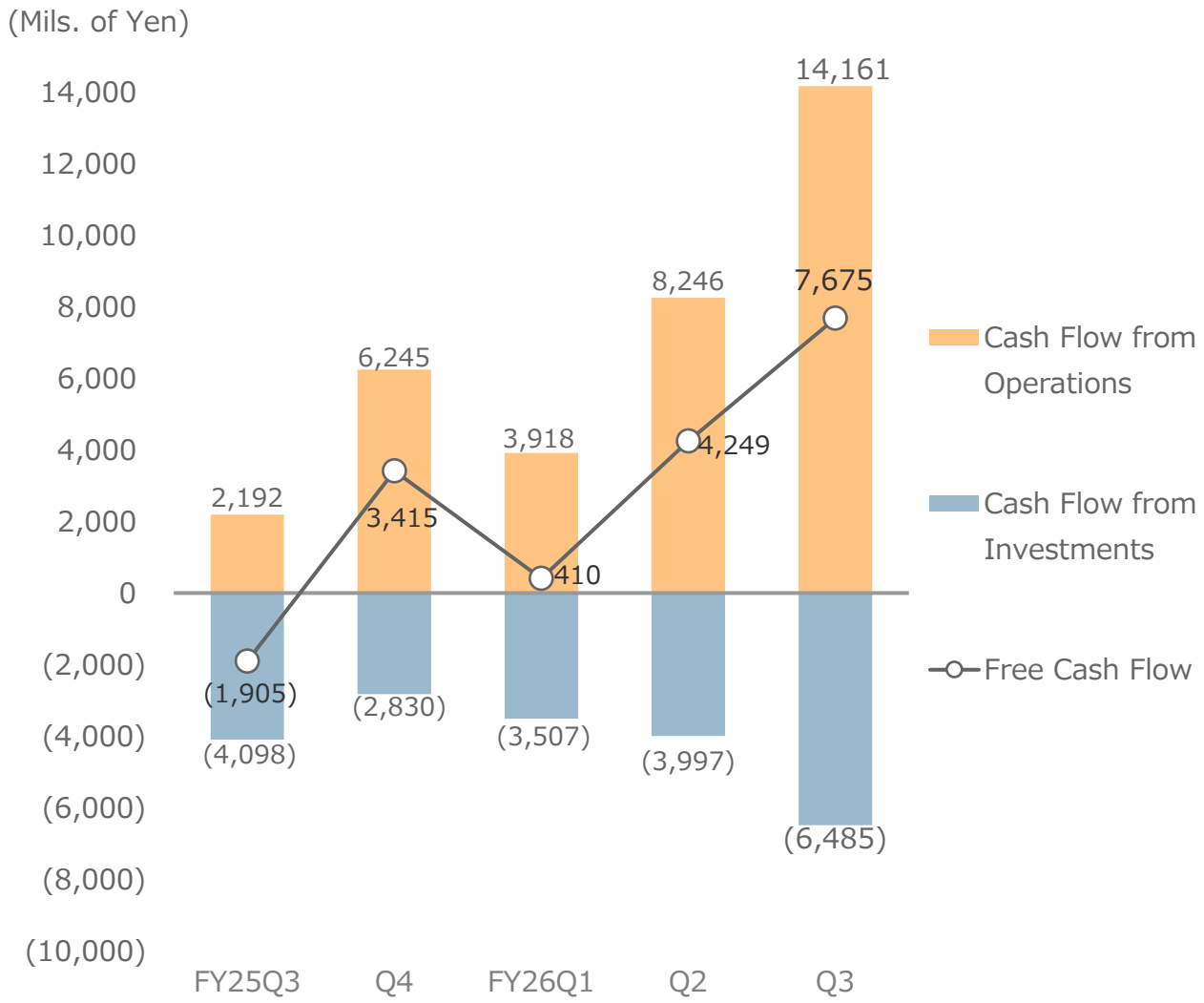
Investment,etc.



	FY25Q3	Q4	FY26Q1	Q2	Q3
R&D	1,673	1,825	1,859	2,047	2,159
CAPEX	2,893	4,563	4,568	4,356	3,569
Depreciation	1,489	1,735	1,624	1,974	2,307

※ Including construction in progress

Cash Flows



© 2026 MICRONICS JAPAN CO., LTD.

Forecasts

© 2026 MICRONICS JAPAN CO., LTD.

Financial Forecast

(Unit : Mils. of Yen)
*Amounts less than one million yen are rounded down

	FY12/2025	FY12/2026					
	Jan.-Dec. (Previous year) ⓐ	As of Aug.12 (Jan.-Dec.) ⓑ	As of Nov.12 (Jan.-Dec.) ⓒ	As of Aug.12		YoY	
				(△) ⓒ-ⓑ	(%)	(△) ⓒ-ⓐ	(%)
Net Sales	70,173	103,800	110,000	+6,200	+6.0%	+39,826	+56.8%
Probe Card	68,525	102,000	108,400	+6,400	+6.3%	+39,874	+58.2%
TE	1,648	1,700	1,600	(100)	(5.9%)	(48)	(2.9%)
Operating profit	16,542	31,400	36,100	+4,700	+15.0%	+19,557	+118.2%
Ordinary profit	17,100	32,000	37,500	+5,500	+17.2%	+20,399	+119.3%
Net Income Attributable to Owner of Parent	12,063	23,000	26,800	+3,800	+16.5%	+14,736	+122.2%
Dividend（Yen）	95	178	208	+30	+16.9%	+113	+118.9%

- FX rate assumption for FY12/2026: JPY 158.00 to USD, JPY 0.10 to KRW

© 2026 MICRONICS JAPAN CO., LTD.

Glossary and Main Products

© 2026 MICRONICS JAPAN CO., LTD.

Glossary

Wafer: Circular crystalline silicon (Si) or gallium arsenide (GaAs) sliced into a thin disk substrate used for semiconductor electrical circuits.

Chip/Die: Dies and chips are small semiconductor devices.
A semiconductor wafer is diced into many pieces, and each of these pieces is called a die or chip.

IC: Integrated circuit.

Memory IC: An integrated circuit made out of millions of capacitors and transistors that can store data such as DRAM, NAND Flash and etc.

Logic IC: An integrated circuit that performs logic functions.

DRAM: Dynamic random access memory.
A type of volatile memory with a wide range of uses including main storage for computers and general-purpose memory.

NAND-Type Flash Memory: A type of non-volatile memory that cannot be deleted even when the external power supply is interrupted. Used for USB memory, digital camera memory cards, mobile music players and mobile phone memory. Created by Toshiba in 1987.

LSI: Large-scale integrated circuit.
Called VLSI or ULSI when the transistor's degree of integration is increased.

Micro Computer: An IC that integrates memory and a microprocessor for arithmetic processing on one chip. Recently, the word "microcomputer" is often used to refer to those incorporated in home appliances or other products for electronic control.

System on Chip (SoC) / System LSI: Large-scale IC containing nearly an entire system on one chip. Combines multiple functions previously spread across multiple ICs onto one chip. Realizes small, high-performance machinery. Mainly used in processors and memory, input/output, interface and telecommunications circuitry.

Flip Chip: Flip chips have bump electrodes on the chip surface for the purpose of high-density surface mounting of IC chips on circuit boards. The bumps and wiring board terminals are connected with solder or conductive adhesive.

Bump: Bumps are solder bumps formed on IC pads. Bumps are normally formed with gold (Au) or solder and are used primarily in flip chips for connection to substrates.

Bonding Pad: Supply of power voltage to the chip and signal exchanges with exterior are normally conducted through the lead. The bonding pads are metal electrodes around the chip connecting this lead with each terminal on internal circuitry.

IoT: Internet of Things, allowing physical devices to be sensed or controlled remotely across existing internet infrastructure.

FPD: Flat panel display.

LCD: liquid crystal display.

© 2026 MICRONICS JAPAN CO., LTD.

Glossary

Wafer Test / Probe Test: An electrical test conducted by placing a probe needle on a wafer chip bonding pad.

Final Test / Package Test: Electrical testing of assembled ICs.

DUT: Device under test.

Area Array: A state which has test pads in a grid array on the surface of a chip.

Cantilever Probe Card: Also called a cantilever needle. A probe card using a one-sided needle probe as a fulcrum. Shaped by hand.

Advanced Probe Card: Probe cards other than the cantilever type.

Vertical Probe Cards: A vertical probe card is a probe card in which probe needles are vertical to the substrate. Vertical probe cards are suitable for area array, small pad, low voltage, low needle pressure, and high frequency measurement.

MEMS: Micro-Electro-Mechanical Systems.

MEMS Type Probe Card: MEMS type probe cards are probe cards using MEMS technology. They have a structure that allows the mechanical movement of probe terminals.

DFT: Design for testability

BIST: Built In Self Test

AI(Artificial Intelligence): The simulation of human intelligence processes by machines. It generally needs various type of semiconductors like image sensors.

Generative AI: automatically creates diverse content, including images, videos, and text. It learns from extensive pre-analyzed data, enabling the generation of new content. High-performance semiconductors like GPUs or HBMs are crucial for effective generative AI.

GPU (Graphics Processing Unit):A semiconductor chip that handles complex data calculations, including 3D graphics processing. It excels in parallel computing. When combined with HBM, it enables even faster performance, especially for generative AI.

HBM (High Bandwidth Memory) : A type of DRAM known for its wide bandwidth and high-power efficiency. By stacking DRAM chips and connecting them to a processor using multiple buses, it achieves fast and large-capacity data transfer. It is primarily packaged with GPUs/CPU and used in HPCs and AI servers.

HPC(High Performance Computing) : A technology that performs complex computational processing on massive data at high speeds. It uses high-performance processors to handle big data efficiently.

General-purpose server : A computer or program that performs necessary processing through a network in response to requests from users.

AI server: A specialized server designed specifically for training and inference of generative AI. It is equipped with powerful CPUs, GPUs, HBM, and other devices, providing higher computational capabilities, large memory storage, high bandwidth, and low latency.

Data center :A facility designed to securely store servers and network equipment. When investments in data centers increase, there is often a higher demand for general-purpose servers, which in turn can lead to an increased need for DRAM chips.

© 2026 MICRONICS JAPAN CO., LTD.

Our Products

Probe Cards

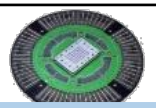
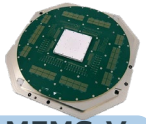
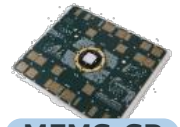
U-Probe: Our core product, realizing the world's first wafer-scale probing created with MJC's proprietary MEMS probe "micro-cantilever" and global top-level thin-film multilayer technology. With a bare minimum of contacting times via a crescent arrangement for DRAM, this product is currently the industry standard. Mainly used for memory testing on DRAM and flash memory.

SP-Probe: Vertical spring pin-type probe card suitable for 12-inch wafer batch measurements. Mainly used for testing NAND flash memory.

MEMS-V / Vertical-Probe: Vertical needle-type probe card used for testing highly integrated, high-speed multi-pin logic devices. Provides flexible support for a variety of pad and fine pitch arrangements and is suitable for multiple individual simultaneous measurements during testing of SoC and other advanced logic devices.

MEMS-SP: Probe card used for MEMS probe developed for testing SoC devices and other flip chip-type logic devices.

Main Applications for MJC Probe Card Products

	Memory		Logic	
	DRAM	Flash	SoC	
Vertical		 SP-Probe	 Vertical-Probe	 SP−Probe
MEMS Type	 U-Probe		 MEMS-V	 MEMS-SP

© 2026 MICRONICS JAPAN CO., LTD.

Our Products

Test Equipment

Semiconductor Tester: A system that gives electrical signals to a semiconductor device to compare output signals with expected values.

Wafer Prober: A system that handles the wafer to make contact in the designated position on the device.

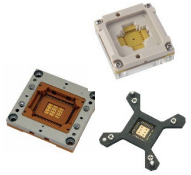
Test Socket: In the final inspection of semiconductor manufacturing, a fixture is used to electrically connect the packaged device and tester. There are two types: ‘J-Contacts,’ suitable for high-frequency and high-performance devices, and ‘BeeContacts,’ which have a unique spring probe structure with excellent contact stability.

RF Probe: RF Probe for High-frequency Measurement, Such as Radio Frequency and Microwave Signals.

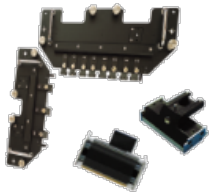
Probe Unit: Probe card with a built-in LCD prober. This blade-type unit developed by MJC is an industry standard.


Semiconductor Tester


Wafer Prober

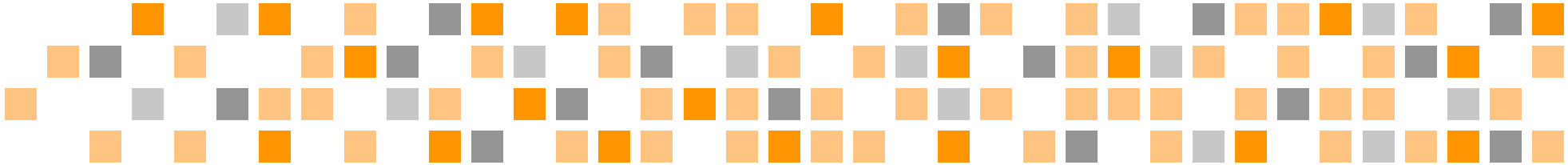

Test Socket


RF Probe


Probe Unit

© 2026 MICRONICS JAPAN CO., LTD.

MJC YOUR Best Partner, MJC Anytime Anywhere



Technical information in this material is provided to explain normal operations and application of our products, not for the purpose of warranty of intellectual property rights and other rights of MJC and a third party or grant of license of the same.

MICRONICS JAPAN CO., LTD.

© 2026 MICRONICS JAPAN CO., LTD.